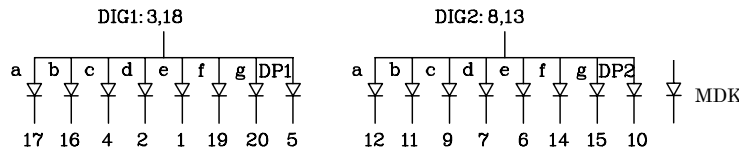
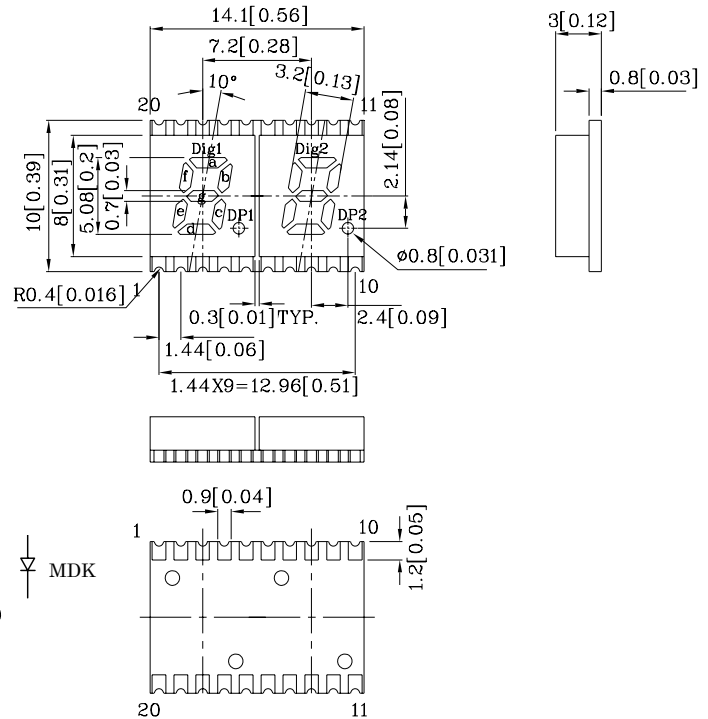


Features

- 0.2 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- GRAY FACE, WHITE SEGMENT.
- PACKAGE : 300PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.



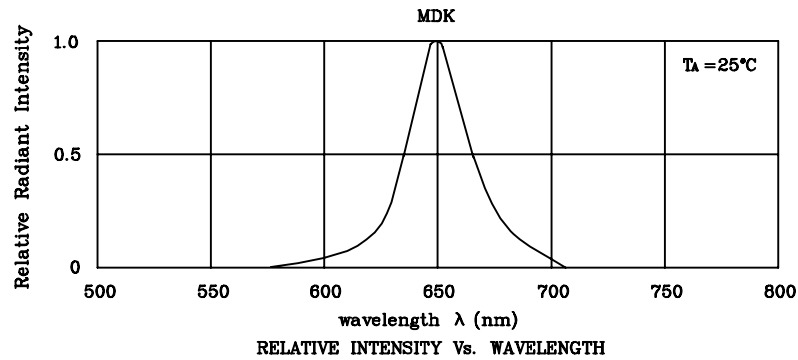
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
3. The gap between the reflector and PCB shall not exceed 0.25mm.

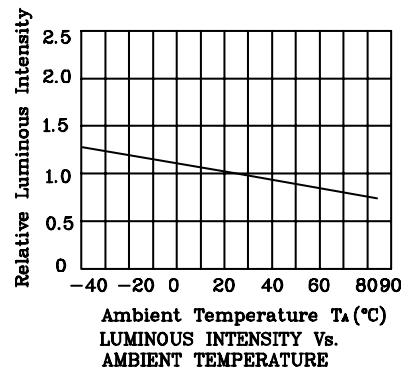
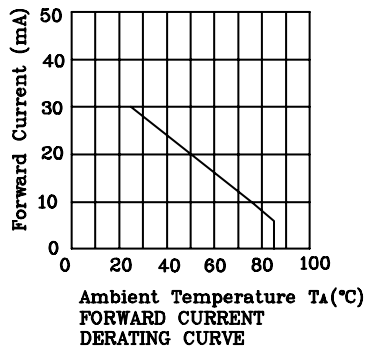
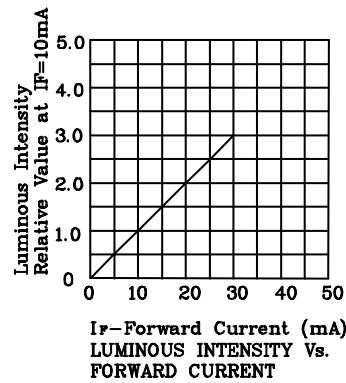
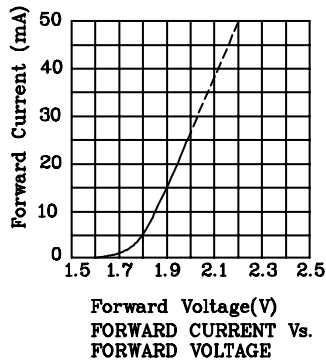
Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)		MDK (InGaAlP)	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	185	mA
Power Dissipation	P_T	75	mW
Operating Temperature	T_A	-40 ~ +85	°C
Storage Temperature	T_{stg}	-40 ~ +85	

Operating Characteristics ($T_A=25^\circ\text{C}$)		MDK (InGaAlP)	Unit
Forward Voltage (Typ.) ($I_F=10\text{mA}$)	V_F	1.85	V
Forward Voltage (Max.) ($I_F=10\text{mA}$)	V_F	2.5	V
Reverse Current (Max.) ($V_R=5\text{V}$)	I_R	10	μA
Wavelength of Peak Emission (Typ.) ($I_F=10\text{mA}$)	λ_P	650	nm
Wavelength of Dominant Emission (Typ.) ($I_F=10\text{mA}$)	λ_D	635	nm
Spectral Line Full Width At Half-Maximum (Typ.) ($I_F=10\text{mA}$)	$\Delta\lambda$	28	nm
Capacitance (Typ.) ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	35	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity ($I_F=10\text{mA}$) ucd	Wavelength nm λ_P	Description	
			min.	typ.		
ZFMDK05A2	Red	InGaAlP	8000	30390	650	Common Anode, Rt. Hand Decimal



❖ MDK



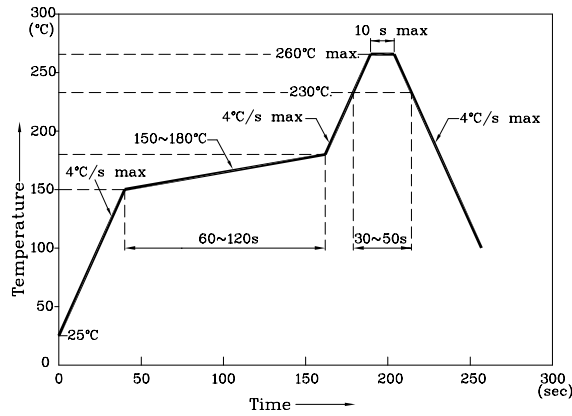
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

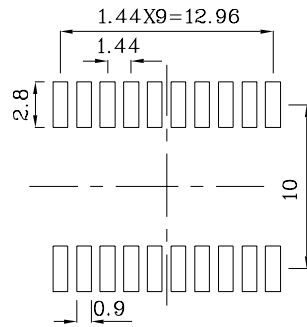
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units : mm; Tolerance: ±0.15)



❖ Tape Specification (Units : mm)

